L Number	Hits	Search Tcxt	DB	Time stamp
1	2	("5173220").PN.	USPAT;	2003/09/25 12:56
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2	8	("4358331"   "4752498"   "4822536"   "4863538"   "4929402"	USPAT	2003/09/25 12:43
]		"4943928"   "4996010"   "4999143").PN.		
3	3943188	metal or glass or ceramic	USPAT;	2003/09/25 12:56
			US-PGPUB;	
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4	1782	stercolithograph\$6	USPAT;	2003/09/25 12:56
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5	1134	(metal or glass or ceramic) and stereolithograph\$6	USPAT;	2003/09/25 13:34
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6	518	264/401.ccls.	USPAT;	2003/09/25 13:34
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7	2631039	encapsul\$5 or mold\$4 or pot\$4 or scal\$4	USPAT;	2003/09/25 13:35
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8	267	264/401.ccls. and (cncapsul\$5 or mold\$4 or pot\$4 or seal\$4)	USPAT;	2003/09/25 13:38
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9	3943188	ceramic or glass or mctal	USPAT;	2003/09/25 13:39
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10	267	(264/401 ccls. and (encapsul\$5 or mold\$4 or pot\$4 or scal\$4)) and	USPAT;	2003/09/25 13:38
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11	203	(264/401.ccls. and (encapsul\$5 or mold\$4 or pot\$4 or seal\$4)) and	USPAT;	2003/09/25 13:38
		(ceramic or glass or metal)	US-PGPUB;	
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	3247516	scmiconduct\$4 or electronic or chip or dic	USPAT;	2003/09/25 13:39
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13	107	((264/40) only and (2022) only 105 on white 4 and 104 on 1	IBM_TDB	2002/00/25 12 25
	107	((264/401.ccls. and (cncapsul\$5 or mold\$4 or pot\$4 or seal\$4)) and	USPAT;	2003/09/25 13:39
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14	3968414	ceramic or glass or metal or hermetic	USPAT;	2003/09/25 13:40
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15	107	(ceramic or glass or metal or hermetic) and (semiconduct\$4 or electronic	USPAT;	2003/09/25 13:54
		or chip or die) and (cncapsul\$5 or mold\$4 or pot\$4 or scal\$4) and	US-PGPUB;	
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